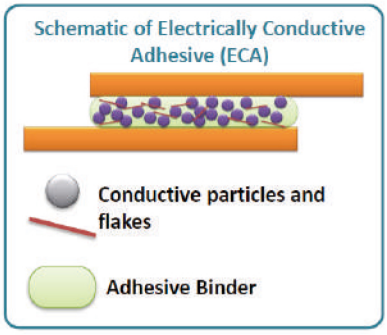
ELECTRICALLY CONDUCTIVE ADHESIVE

Conductive adhesives are widely used in the field of microelectronic assembling, suitable for connecting fine wires, printed circuits, electroplated substrates, connecting to ceramic metal layers and metal chassis. It can replace high-temperature soldering technology, with applications in telecommunications, automotive, medical equipment and electromagnetic compatibility (EMC) industries. This conductive adhesive also provides good bonding performance in ferroelectric devices, battery terminal connections and other areas.

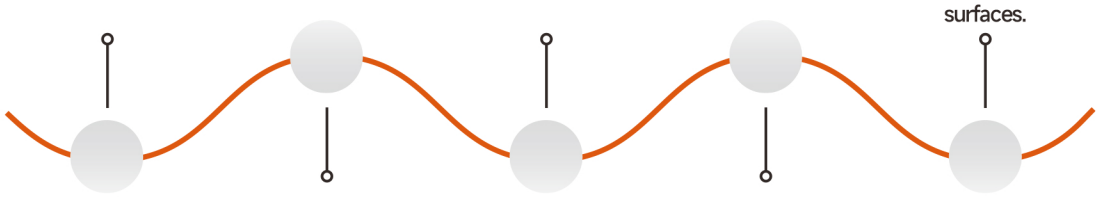


PRODUCT FEATURES

High line resolution which is suitable for finer lead spacing and high-density I/O assembly.

Low-temperature connection capability which is suitable for heating-sensitive device.

Compatible with various substrates: Ceramics glass, and other non-solderable surfaces.



Lead-free and free for other toxic metals.

Excellent flexibility and fatigue resistance.

PRODUCT PROPERTIES

ITEM		SPECIFICATION RE-ECA-3020DC
Classification		One Component Thermo-Setting Adhesive
Composition	Binder	N/A
	Conductive filler	Silver (≥68%)
	Solid Content(%)	>99.5 @150°C/30min
Properties	Viscosity : cps (@25°C)(Brookfield HBDV-II, #14, 10rpm)	55,000 ± 5,000 (adjustable)
Curing condition	Temperature × Time	≥ 120°C × 15 sec ≥ 150°C × 10 sec ≥ 80°C × 1 hour
Use		Conductive Adhesive
Working method		Dispensing
Characteristics	Conductivity : Ω • ㎝(Depends on curing condition)	< 9.0×10^{-5} (@150°C/30 sec.)
Shelf life	At 20°C	≥3 days
	At < -20 °C	6 months
Container		10ml / 30ml syringe